<u>IN THE UNITED STATES PATENT AND TRADEMARK OFF</u>

Serial No.:

09/831,763

Filed:

May 11, 2001

Inventor(s):

Heinrich Meyer et al.

For:

Method of Galvanically Forming Conductor Structures of High-Purity Copper in the Production

of Integrated Circuits

Examiner:

Mutschler, Brian L.

Art Unit:

1753

Attorney Docket No.: 071-01

Commissioner for Patents P.O. Box 1450

Alexandria, VA 22313-1450

CERTIFICATE OF MAILING

DATE OF DEPOSIT: November 24, 2003 I hereby certify that this correspondence is being deposited with the United States Postal Service, postage paid, as first class mail under 37 C.F.R. §1.8, on the date indicated above and is addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Name of person

mailing paper or fee: Ourmazd S. Ojan

**COVER LETTER AND CERTIFICATE OF MAILING** 

Sir:

Enclosed and attached hereto are the following:

- 1) This cover letter (in triplicate);
- Terminal disclaimer (1 page);
- Petition for two-month extension of time (1 page; in duplicate);
- 4) Amendment Transmittal Form (in duplicate);
- 5) Amendment (9 pages);
- 6) Clean copy of Substitute Specification (23 pages including cover sheet);
- 7) Marked-up Substitute Specification (23 pages including cover sheet);
- 8) Replacement Abstract (2 pages including cover sheet);
- 9) Check in the amount of \$420.00 for the extension fee;

- 10) Check in the amount of \$110.00 for the disclaimer fee; and
- 11) Postcard to be date stamped and returned by PTO.

No additional fees are believed to be required at this time. In the event that additional fees are required with respect to this communication, the Commissioner is hereby authorized to charge any such fees, or credit any overpayment, to Paul & Paul deposit account number 16-0750.

Respectfully submitted,

November 24, 2003

Ourmazd S. Ojan Reg. No. 38,065

Paul & Paul

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Order No. <u>1895</u>

## AMENDMENT TRANSMITTAL LETTER (Large Entity) Docket No. Applicant(s): Heinrich Meyer et al. 071-01 Serial No. Filing Date Examiner Group Art Unit 09/831,763 05/11/2001 Brian L. Mutschler 1753 Invention OIPE Method for Galvanically Forming Conductor Structures of High-Purity Copper in the Production of Integrated Circuits DECO 8 2003 TO THE ASSISTANT COMMISSIONER FOR PATENTS: vith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below. **CLAIMS AS AMENDED CLAIMS REMAINING** HIGHEST # NUMBER EXTRA ADDITIONAL RATE AFTER AMENDMENT PREV. PAID FOR CLAIMS PRESENT FEE **TOTAL CLAIMS** 17 20 0|x\$18.00 \$0.00 INDEP. CLAIMS 1 0|x\$86.00 \$0.00 Multiple Dependent Claims (check if applicable) \$0.00 TOTAL ADDITIONAL FEE FOR THIS AMENDMENT \$0.00 No additional fee is required for amendment. Please charge Deposit Account No. in the amount of A duplicate copy of this sheet is enclosed. ☐ A check in the amount of to cover the filing fee is enclosed. The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 16-0750 A duplicate copy of this sheet is enclosed. Any additional filing fees required under 37 C.F.R. 1.16. Any patent application processing fees under 37 CFR 1.17. Dated: Ourmazd S. Ojan Reg. No. 38,065 Paul & Paul I certify that this document and fee is being deposited 2000 Market Street on 11/24/2003 with the U.S. Postal Service as **Suite 2900** first class mail under 37 C.F.R. 1.8 and is addressed to the Philadelphia, PA 19103

Phone: (215) 568-4900; FAX: (215) 567-5057

Assistant Commissioner for Patents, Washington, D.C. 20231.

Signature of Person Mailing Correspondence

Ourmazd S. Ojan

Typed or Printed Name of Person Mailing Correspondence